

L Number	Hits	Search Text	DB	Time stamp
1	459667	wafer chip die dice	USPAT; US-PGPUB	2002/09/30 10:30
2	4473	((wafer chip die dice) and (quality near10 test\$3))	USPAT; US-PGPUB	2002/09/30 10:31
3	2718	((wafer chip die dice) and (quality near10 test\$3)) and chip	USPAT; US-PGPUB	2002/09/30 10:31
4	1339	((wafer chip die dice) and (quality near10 test\$3)) and chip) and memory	USPAT; US-PGPUB	2002/09/30 09:20
5	702	((wafer chip die dice) and (quality near10 test\$3)) and chip) and memory) and semiconductor	USPAT; US-PGPUB	2002/09/30 09:21
8	111	((wafer chip die dice) and (quality near10 test\$3)) and chip) and memory) and semiconductor	US-PGPUB	2002/09/30 09:21
6	591	((wafer chip die dice) and (quality near10 test\$3)) and chip) and memory) and semiconductor	USPAT	2002/09/30 09:45
9	39675	semiconductor near10 chip	USPAT	2002/09/30 09:46
10	13489	(semiconductor near10 chip) and test\$3	USPAT	2002/09/30 09:46
11	6216	((semiconductor near10 chip) and test\$3) and (dic\$3 singulat\$3 divid\$3)	USPAT	2002/09/30 10:34
12	5443	((semiconductor near10 chip) and test\$3) and (dic\$3 singulat\$3 divid\$3)) and result	USPAT	2002/09/30 09:48
13	79	((semiconductor near10 chip) and test\$3) and (test\$3 near20 result\$3 near50 (dic\$3 singulat\$3 divid\$3))	USPAT	2002/09/30 10:26
14	593876	wafer chip die dice	EPO; JPO; DERWENT; IBM_TDB	2002/09/30 10:31
15	414	((wafer chip die dice) and (quality near10 test\$3))	EPO; JPO; DERWENT; IBM_TDB	2002/09/30 10:31
16	246	((wafer chip die dice) and (quality near10 test\$3)) and chip	EPO; JPO; DERWENT; IBM_TDB	2002/09/30 10:33
17	63267	semiconductor near10 chip	EPO; JPO; DERWENT; IBM_TDB	2002/09/30 10:33
18	3803	(semiconductor near10 chip) and test\$3	EPO; JPO; DERWENT; IBM_TDB	2002/09/30 10:33
19	264	((semiconductor near10 chip) and test\$3) and (dic\$3 singulat\$3 divid\$3)	EPO; JPO; DERWENT; IBM_TDB	2002/09/30 10:34